



**THE DATASHEET OF  
FDB28N30TM**



# MOSFET - UniFET™, N-Channel

## 300 V, 28 A, 129 mΩ

### FDB28N30TM

#### Description

UniFET™ MOSFET is ON Semiconductor's high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.

#### Features

- Typical  $R_{DS(on)} = 108 \text{ m}\Omega$  at  $V_{GS} = 10 \text{ V}$ ,  $I_D = 14 \text{ A}$
- Low Gate Charge (Typical  $Q_g = 39 \text{ nC}$ )
- Low Reverse Transfer Capacitance  $C_{rss}$  (Typical  $C_{rss} = 35 \text{ pF}$ )
- 100% Avalanche Tested
- This Device is Pb-Free and is RoHS Compliant

#### Applications

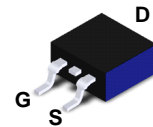
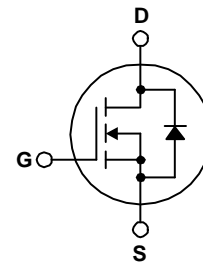
- Uninterruptible Power Supply
- AC-DC Power Supply



**ON Semiconductor®**

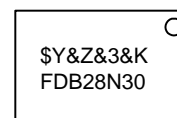
[www.onsemi.com](http://www.onsemi.com)

#### N-Channel



**D<sup>2</sup>PAK-3 (TO-263, 3-LEAD)  
CASE 418AJ**

#### MARKING DIAGRAM



\$Y	= ON Semiconductor Logo
&Z	= Assembly Plant Code
&3	= Numeric Date Code
&K	= Lot Code
FDB28N30	= Specific Device Code

#### ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

# FDB28N30TM

## MOSFET MAXIMUM RATINGS (T<sub>C</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Ratings	Units
V <sub>DSS</sub>	Drain to Source Voltage	300	V
V <sub>GSS</sub>	Gate to Source Voltage	±30	V
I <sub>D</sub>	Drain Current –Continuous (T <sub>C</sub> = 25°C)	28	A
	–Continuous (T <sub>C</sub> = 100°C)	19	
I <sub>DM</sub>	Drain Current –Pulsed (Note 1)	112	A
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)	588	mJ
I <sub>AR</sub>	Avalanche Current (Note 1)	28	A
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)	25	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	4.5	V/ns
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> = 25°C)	250	W
	–Derate above 25°C	2.0	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	–55 to +150	°C
T <sub>L</sub>	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 seconds	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Repetitive rating: pulse-width limited by maximum junction temperature
2. L = 1.5 mH, I<sub>AS</sub> = 28 A, V<sub>DD</sub> = 50 V, R<sub>G</sub> = 25 Ω, starting T<sub>J</sub> = 25°C
3. I<sub>SD</sub> ≤ 28 A, di/dt ≤ 200 A/μs, V<sub>DD</sub> ≤ BV<sub>DSS</sub>, starting T<sub>J</sub> = 25°C

## THERMAL CHARACTERISTICS

Symbol	Parameter	Ratings	Units
R <sub>θJC</sub>	Maximum Thermal Resistance, Junction to Case	0.5	°C/W
R <sub>θJA</sub>	Maximum Thermal Resistance, Junction to Ambient (1 in <sup>2</sup> Pad of 2-oz Copper)	40	°C/W
R <sub>θJA</sub>	Maximum Thermal Resistance, Junction to Ambient (Minimum Pad of 2-oz Copper)	62.5	°C/W

## PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Mark	Package	Shipping†
FDB28N30TM	FDB28N30	D <sup>2</sup> PAK-3 (TO-263, 3-LEAD) (Pb-Free)	800 units / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D

# FDB28N30TM

## ELECTRICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
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### OFF CHARACTERISTICS

BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	I <sub>D</sub> = 250 μA, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 25°C	300			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, referenced to 25°C		0.4		V/°C
I <sub>DSS</sub>	Drain-to-Source Leakage Current	V <sub>DS</sub> = 300 V, V <sub>GS</sub> = 0 V			1	μA
		V <sub>DS</sub> = 240 V, T <sub>C</sub> = 125°C			10	
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>GS</sub> = ±30 V, V <sub>DS</sub> = 0 V			±100	nA

### ON CHARACTERISTICS

V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 250 μA	3.0		5.0	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 14 A		0.108	0.129	Ω
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 14 A		24.8		s

### DYNAMIC CHARACTERISTICS

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz		1690	2250	pF
C <sub>oss</sub>	Output Capacitance			305	405	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			35	50	pF
Q <sub>g</sub>	Total Gate Charge at 10 V	V <sub>DS</sub> = 240 V, I <sub>D</sub> = 28 A, V <sub>GS</sub> = 10 V (Note 4)		39	50	nC
Q <sub>gs</sub>	Gate to Source Gate Charge			12		nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge			17		nC

### SWITCHING CHARACTERISTICS

t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 150 V, I <sub>D</sub> = 28 A, V <sub>GS</sub> = 10V, R <sub>G</sub> = 25 Ω (Note 4)		35	80	ns
t <sub>r</sub>	Turn-On Rise Time			135	280	ns
t <sub>d(off)</sub>	Turn-Off Delay Time			79	168	ns
t <sub>f</sub>	Turn-Off Fall Time			69	148	ns

### DRAIN-SOURCE DIODE CHARACTERISTICS

I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current				28	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current				112	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 28 A			1.4	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 28 A, dI <sub>F</sub> /dt = 100 A/μs		279		ns
Q <sub>rr</sub>	Reverse Recovery Charge			2.7		μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

TYPICAL PERFORMANCE CHARACTERISTICS

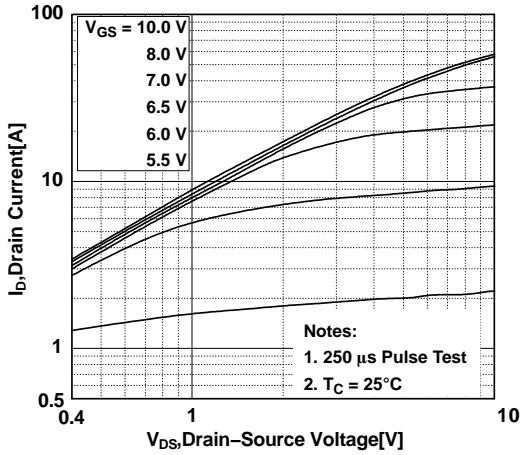


Figure 1. On-Region Characteristics

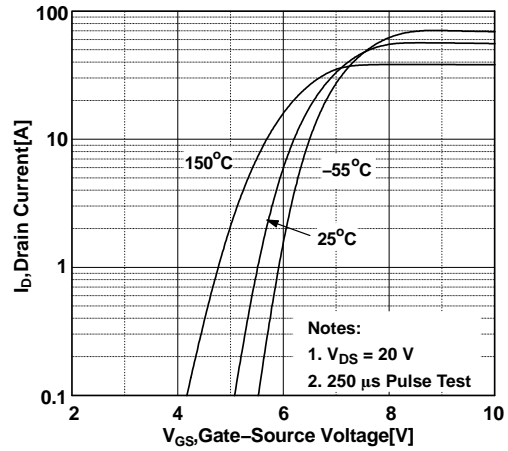


Figure 2. Transfer Characteristics

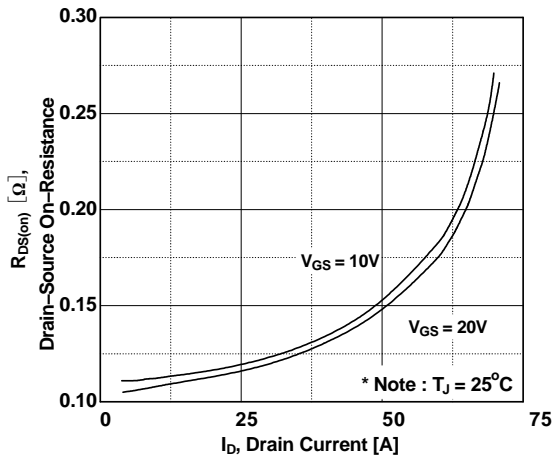


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

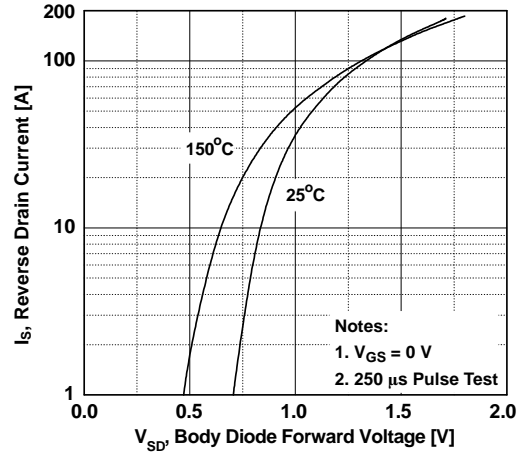


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

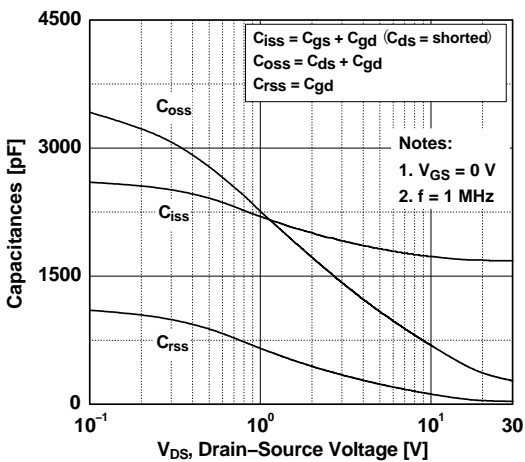


Figure 5. Capacitance Characteristics

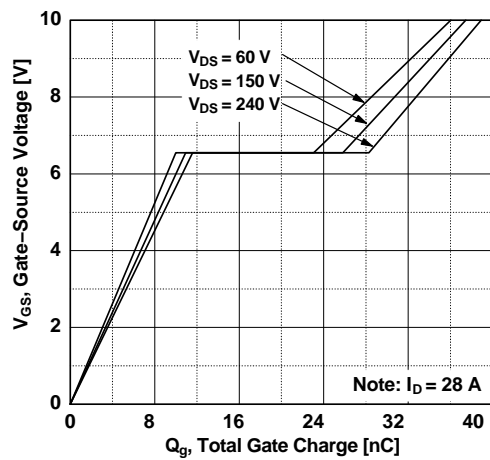


Figure 6. Gate Charge Characteristics

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

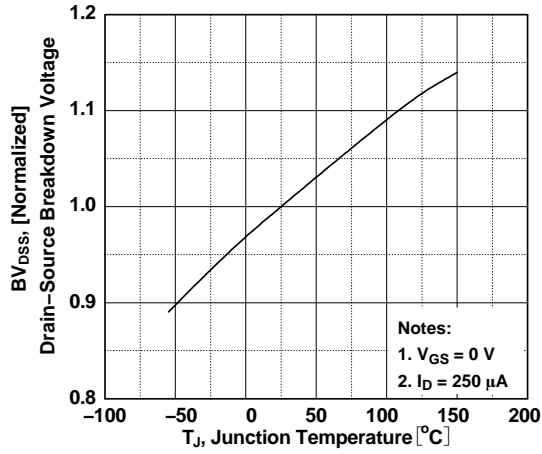


Figure 7. Breakdown Voltage Variation vs. Temperature

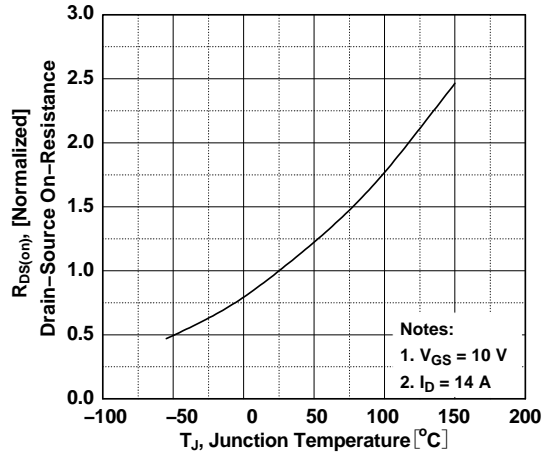


Figure 8. On-Resistance Variation vs. Temperature

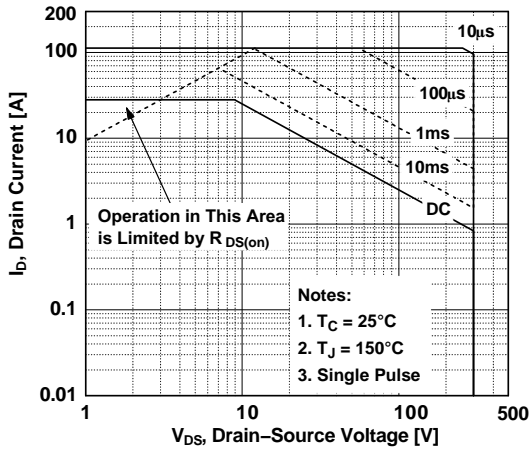


Figure 9. Maximum Safe Operating Area

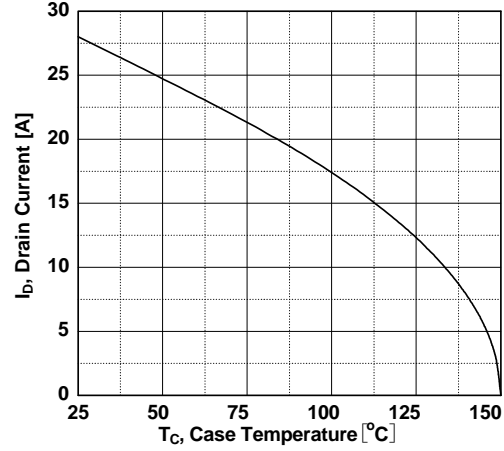


Figure 10. Maximum Drain Current vs. Case Temperature

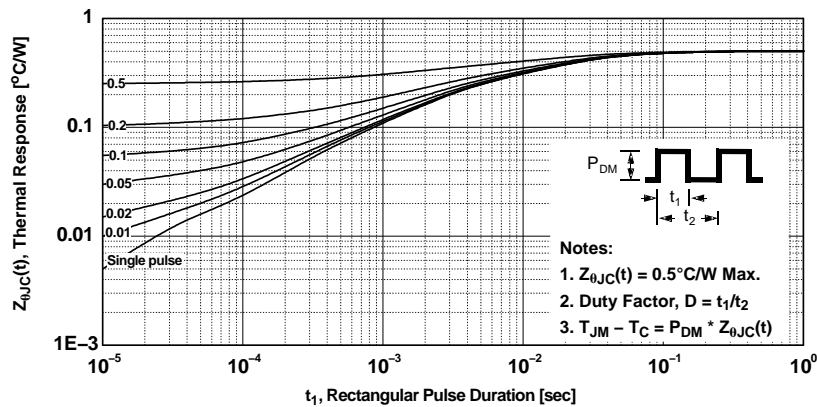


Figure 11. Transient Thermal Response Curve

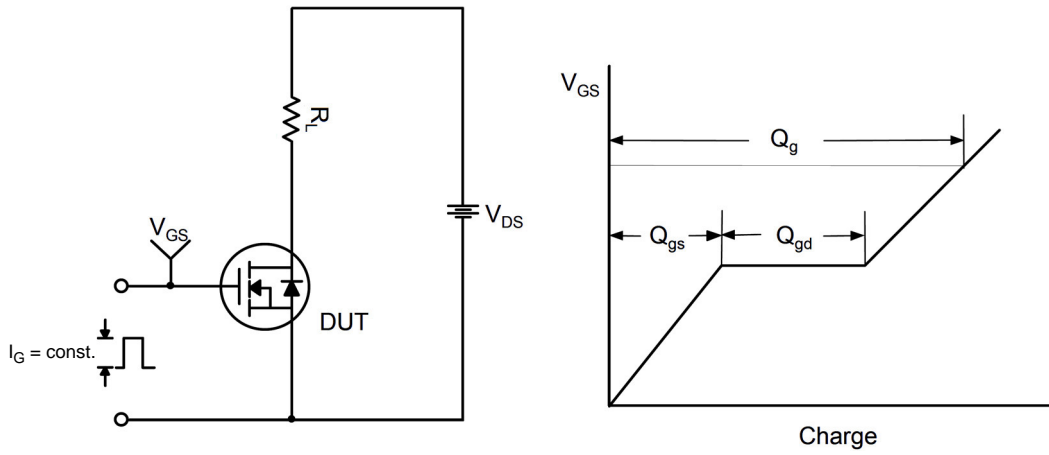


Figure 12. Gate Charge Test Circuit & Waveform

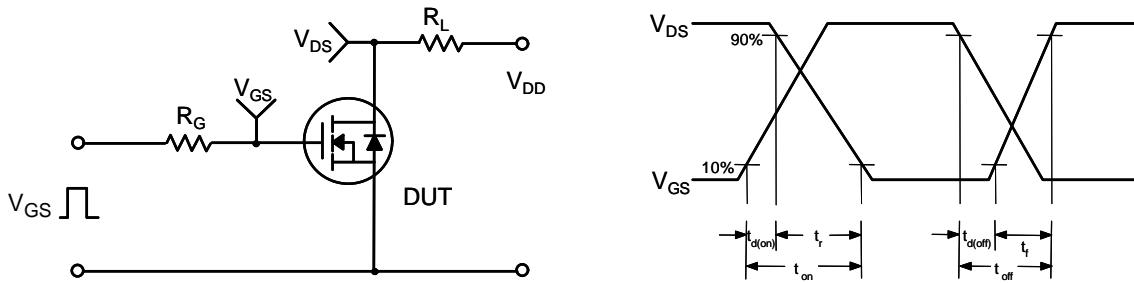


Figure 13. Resistive Switching Test Circuit & Waveform

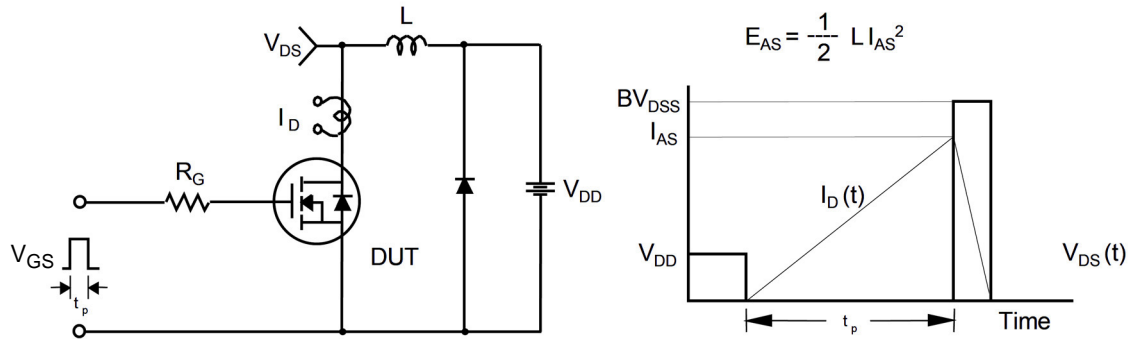


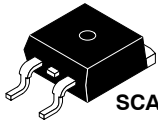
Figure 14. Unclamped inductive Switching Test Circuit & Waveform



# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

ON Semiconductor®



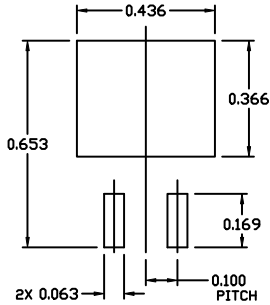
SCALE 1:1

### D<sup>2</sup>PAK-3 (TO-263, 3-LEAD)

#### CASE 418AJ

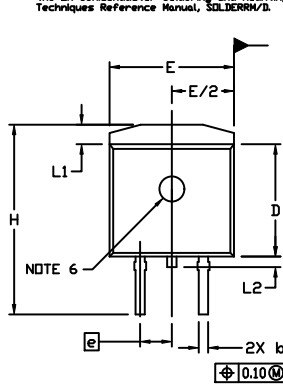
#### ISSUE F

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#### RECOMMENDED MOUNTING FOOTPRINT

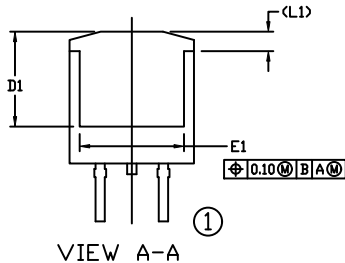
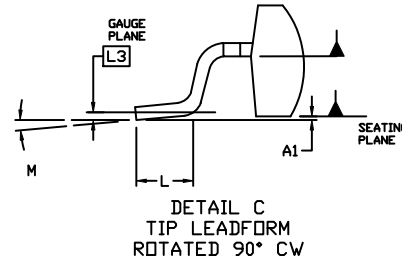
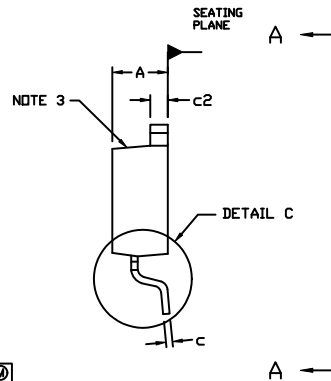
■ For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



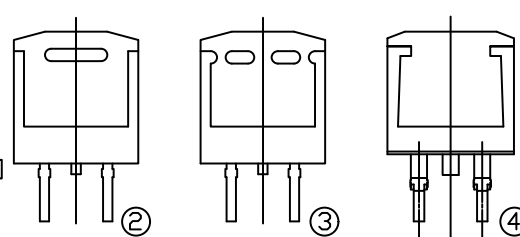
#### NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- CONTROLLING DIMENSION: INCHES
- CHAMFER OPTIONAL.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.005 PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AT DATUM H.
- THERMAL PAD CONTOUR IS OPTIONAL WITHIN DIMENSIONS E, L1, D1, AND E1.
- OPTIONAL MOLD FEATURE.
- ①, ② ... OPTIONAL CONSTRUCTION FEATURE CALL OUTS.

DIM	INCHES		MILLIMETERS	
	MIN.	MAX.	MIN.	MAX.
A	0.160	0.190	4.06	4.83
A1	0.000	0.010	0.00	0.25
b	0.020	0.039	0.51	0.99
c	0.012	0.029	0.30	0.74
c2	0.045	0.065	1.14	1.65
D	0.330	0.380	8.38	9.65
D1	0.260	---	6.60	---
E	0.380	0.420	9.65	10.67
E1	0.245	---	6.22	---
e	0.100	BSC	2.54	BSC
H	0.575	0.625	14.60	15.88
L	0.070	0.110	1.78	2.79
L1	---	0.066	---	1.68
L2	---	0.070	---	1.78
L3	0.010	BSC	0.25	BSC
M	0*	8*	0*	8*

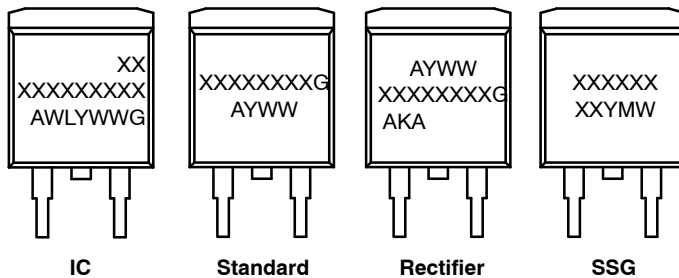


VIEW A-A



VIEW A-A  
OPTIONAL CONSTRUCTIONS

#### GENERIC MARKING DIAGRAMS\*



IC

Standard

Rectifier

SSG

- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- W = Week Code (SSG)
- M = Month Code (SSG)
- G = Pb-Free Package
- AKA = Polarity Indicator

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	D <sup>2</sup> PAK-3 (TO-263, 3-LEAD)	PAGE 1 OF 1

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- ✓ Obsolete Management
- ✓ Cost Control Management
- ✓ Shortage Management
- ✓ Alternative Solution
- ✓ Excess Inventory Management